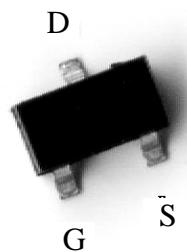


P-Channel Logic Level Enhancement Mode MOSFET

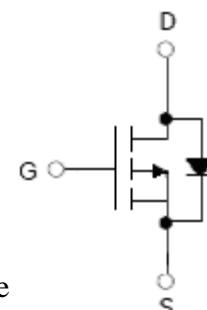
Features:

- 1.8V gate rated
- Advanced trench process technology
- High density cell design for ultra low on resistance
- Pb-free lead plating and halogen-free package

SOT-23



BVDSS	-20V
ID@VGS=-4.5V, TA=25°C	-4.9A
RDS(on)(TYP)	
VGS=-4.5V, ID=-4.3A	39mΩ
VGS=-2.5V, ID=-2.5A	51mΩ
VGS=-1.8V, ID=-2A	75mΩ



G : Gate

S : Source

D : Drain

Ordering Information

Device	Package	Shipping
KWP3413SN3	SOT-23 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Absolute Maximum Ratings ($T_a=25^\circ C$)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current @ $T_A=25^\circ C$, $V_{GS}=-4.5V$	I_D	-4.9	A
Continuous Drain Current @ $T_A=70^\circ C$, $V_{GS}=-4.5V$	I_D	-3.9	A
Pulsed Drain Current (Note 1&2)	I_{DM}	-35	A
Maximum Power Dissipation @ $T_A=25^\circ C$	P_D	1.38	W
Maximum Power Dissipation @ $T_A=70^\circ C$		0.88	
Operating Junction and Storage Temperature	T_j, T_{stg}	-55~+150	°C

Note : 1. Pulse width limited by maximum junction temperature.
 2. Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient (Note)	$R_{th,ja}$	90	°C/W

Note : Surface mounted on 1 in² copper pad of FR-4 board, 270°C/W when mounted on minimum copper pad.

Electrical Characteristics ($T_j=25^\circ C$, unless otherwise specified)

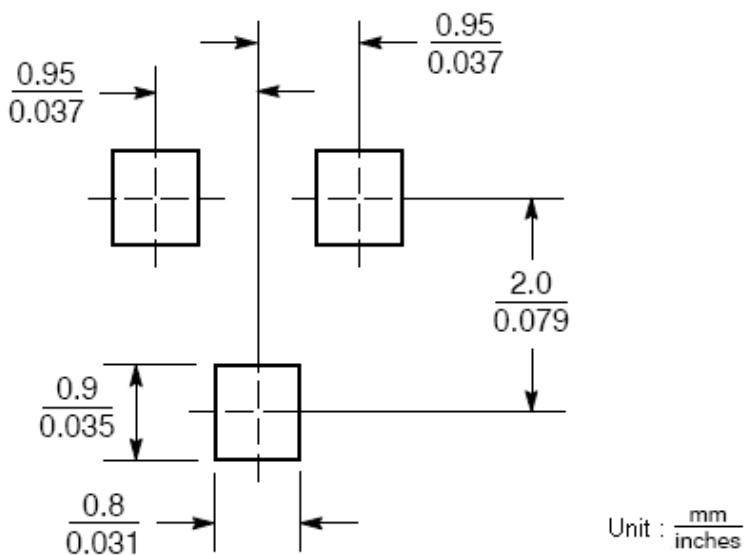
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	-20	-	-	V	$V_{GS}=0V, I_D=-250\mu A$
$V_{GS(th)}$	-0.4	-	-1.0		$V_{DS}=V_{GS}, I_D=-250\mu A$
I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 12V, V_{DS}=0V$
I_{DSS}	-	-	-1	μA	$V_{DS}=-20V, V_{GS}=0V$
	-	-	-10		$V_{DS}=-20V, V_{GS}=0V, T_j=55^\circ C$
$*R_{DS(ON)}$	-	39	50	m \wedge	$V_{GS}=-4.5V, I_D=-4.3A$
	-	51	65		$V_{GS}=-2.5V, I_D=-2.5A$
	-	75	100		$V_{GS}=-1.8V, I_D=-2.0A$
Dynamic					
C_{iss}	-	1220	-	pF	$V_{DS}=-10V, V_{GS}=0V, f=1MHz$
C_{oss}	-	103	-		
Cr_{ss}	-	92	-		
$*t_{d(ON)}$	-	12.5	-	ns	$V_{DS}=-10V, I_D=-1A, V_{GS}=-4.5V, R_D=10\Omega, R_G=6\Omega$
$*t_r$	-	12	-		
$*t_{d(OFF)}$	-	70	-		
$*t_f$	-	20	-		
$*Q_g$	-	10	-	nC	$V_{DS}=-10V, I_D=-4.3A, V_{GS}=-4.5V$
$*Q_{gs}$	-	1.9	-		
$*Q_{gd}$	-	2.7	-		

Source-Drain Diode

*I _{SD}	-	-	-1.3	A	
*I _{SM}	-	-	-35		
*V _{SD}	-	-0.76	-1	V	V _{GS} =0V, I _S =-1.3A
*t _{rr}	-	23	-	ns	
*Q _{rr}	-	8.5	-	nC	I _S =-1.3A, V _{GS} =0V, dI/dt=100A/μs

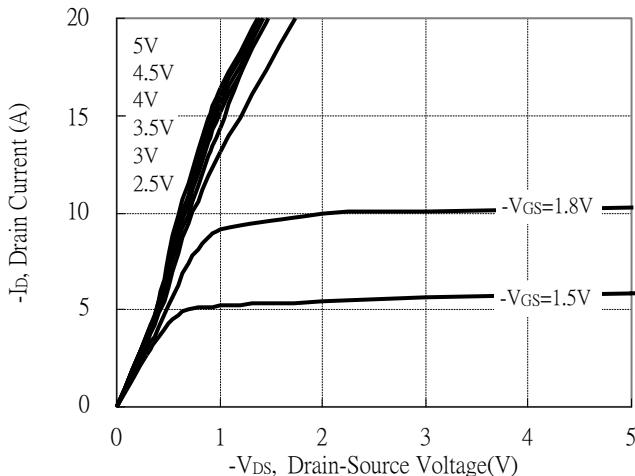
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Recommended Soldering Footprint

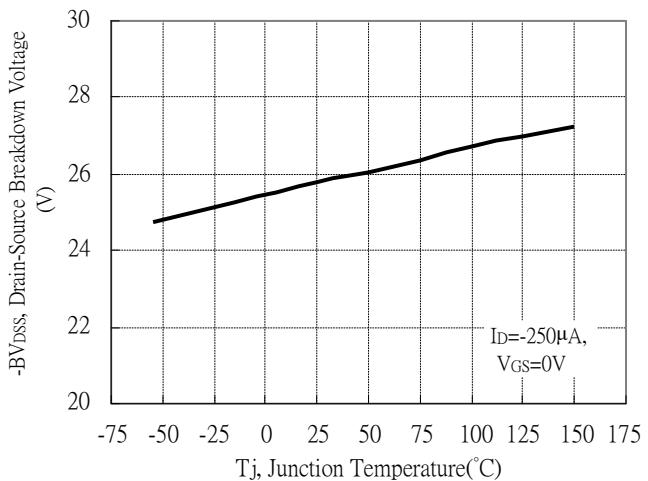


Typical Characteristics

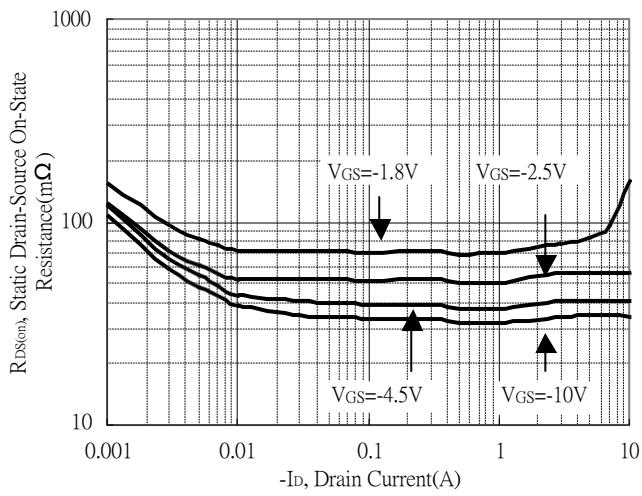
Typical Output Characteristics



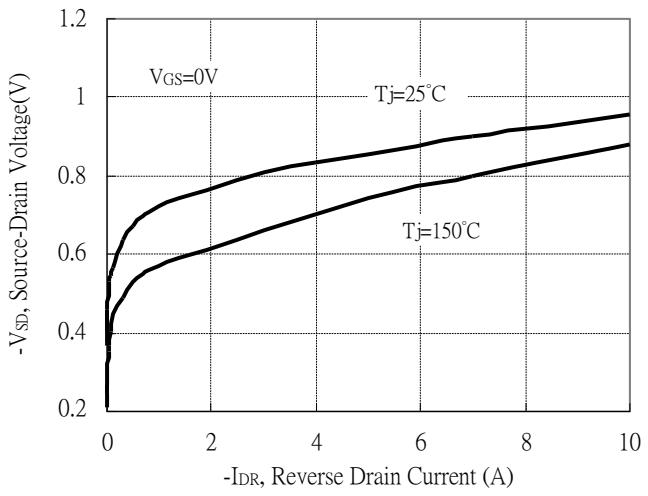
Breakdown Voltage vs Ambient Temperature



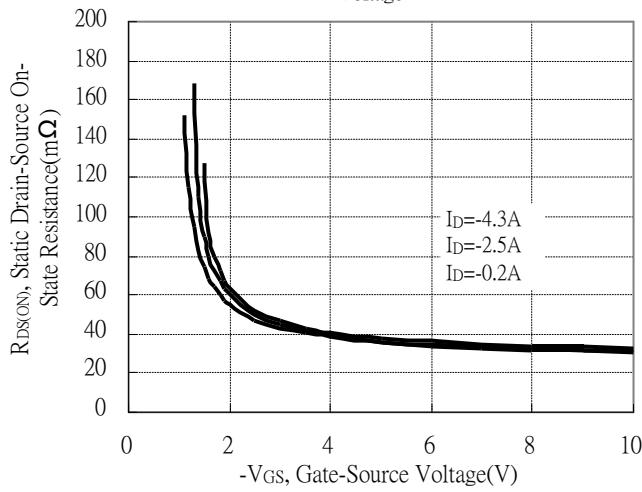
Static Drain-Source On-State resistance vs Drain Current



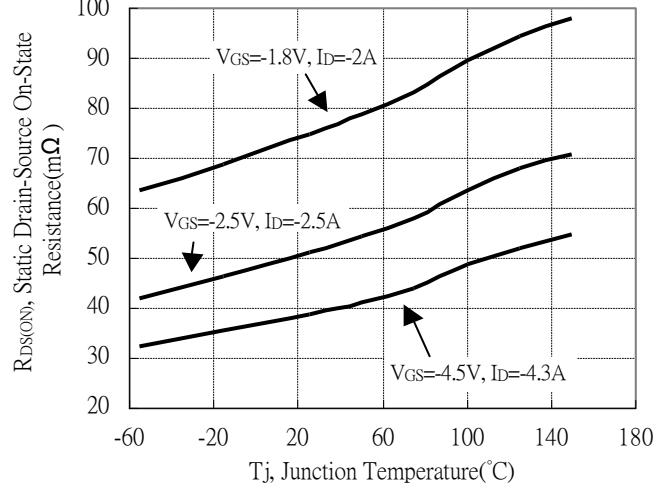
Reverse Drain Current vs Source-Drain Voltage



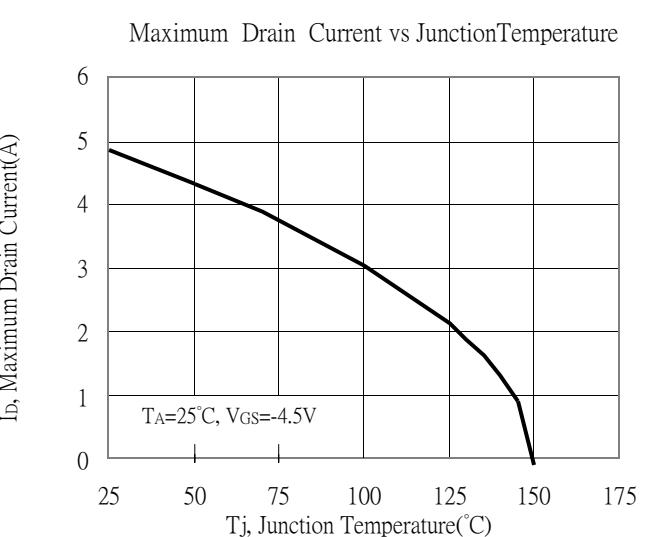
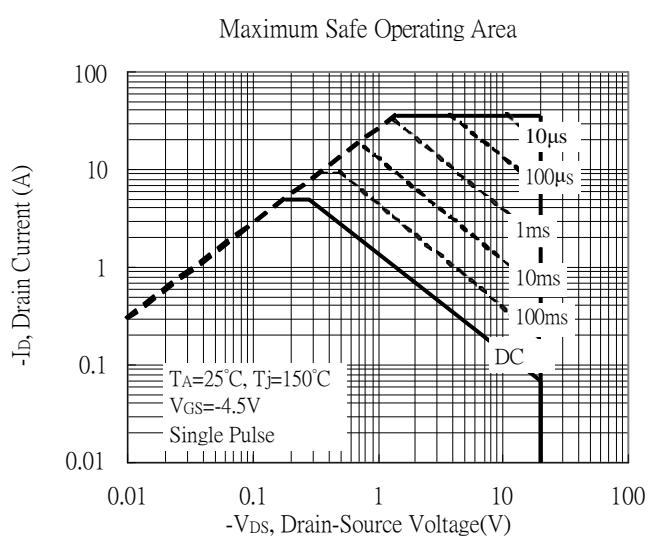
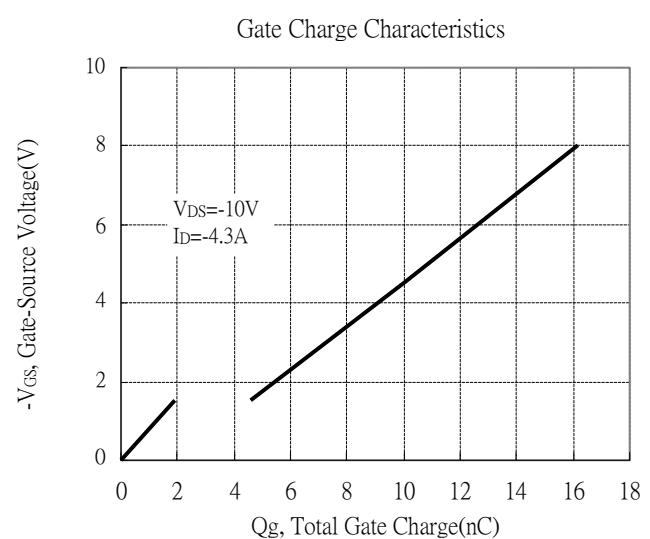
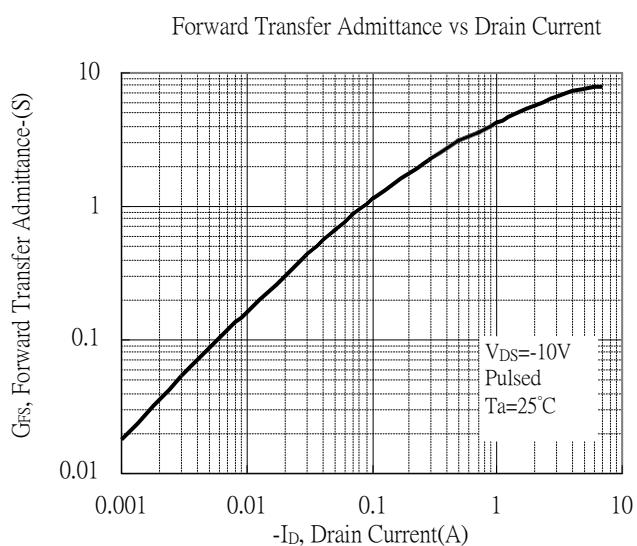
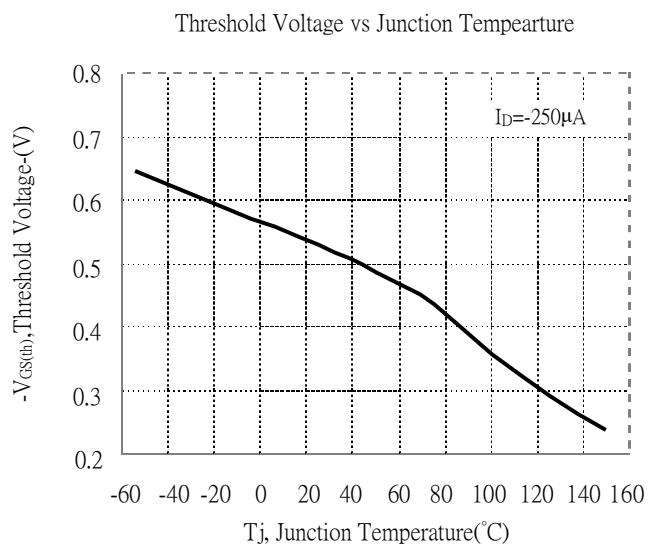
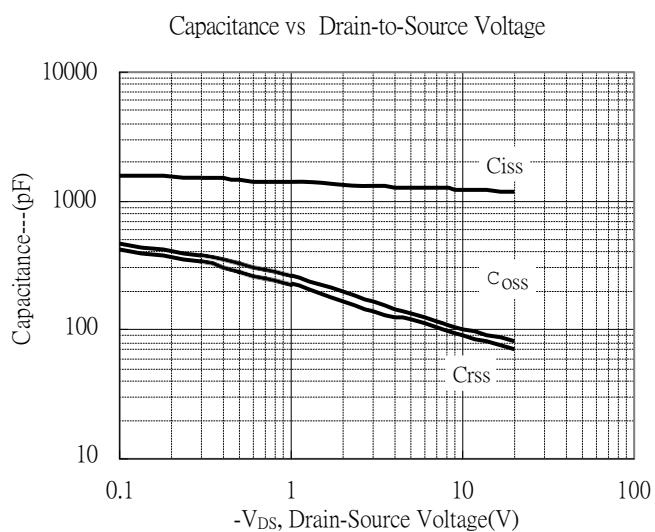
Static Drain-Source On-State Resistance vs Gate-Source Voltage



Drain-Source On-State Resistance vs Junction Temperature

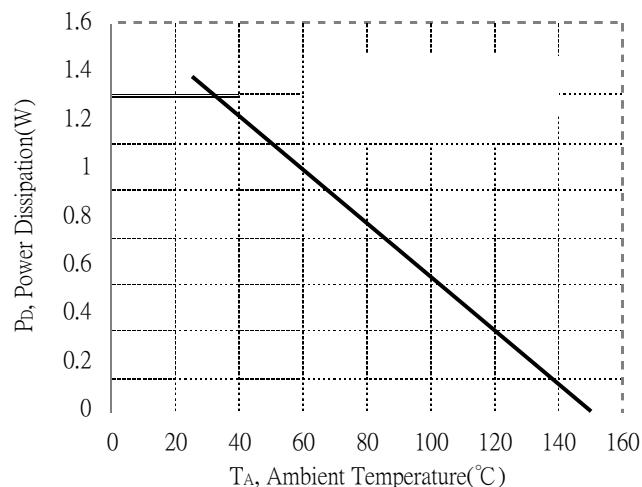


Typical Characteristics(Cont.)

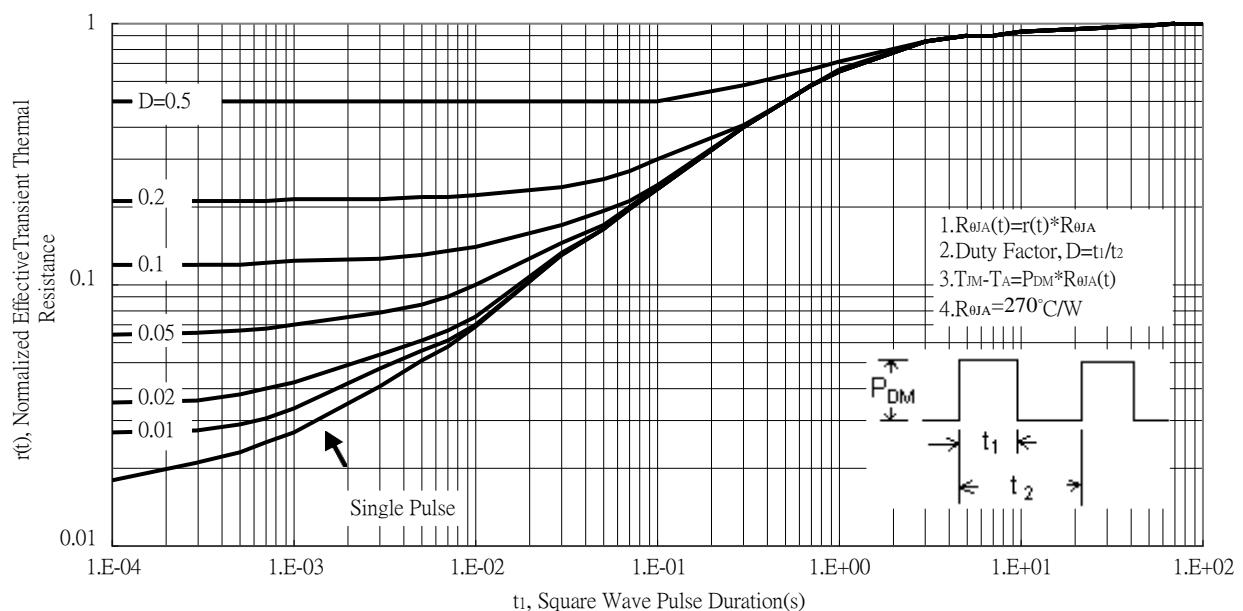


Typical Characteristics(Cont.)

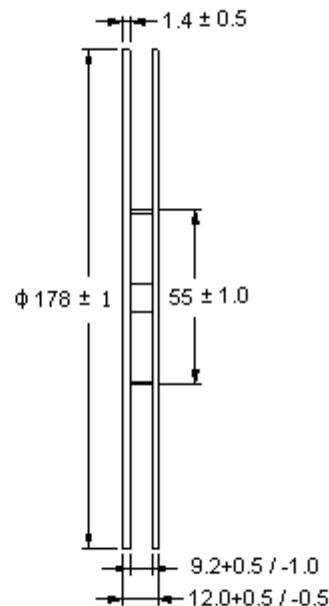
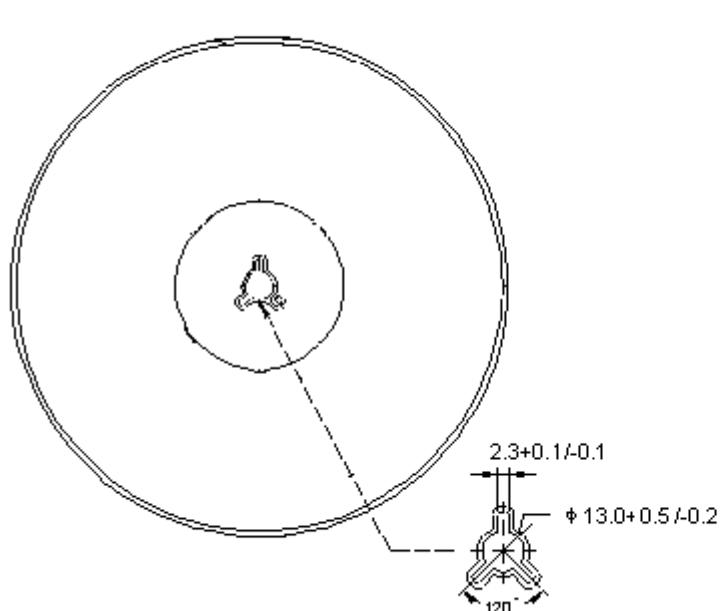
Power Derating Curve



Transient Thermal Response Curves

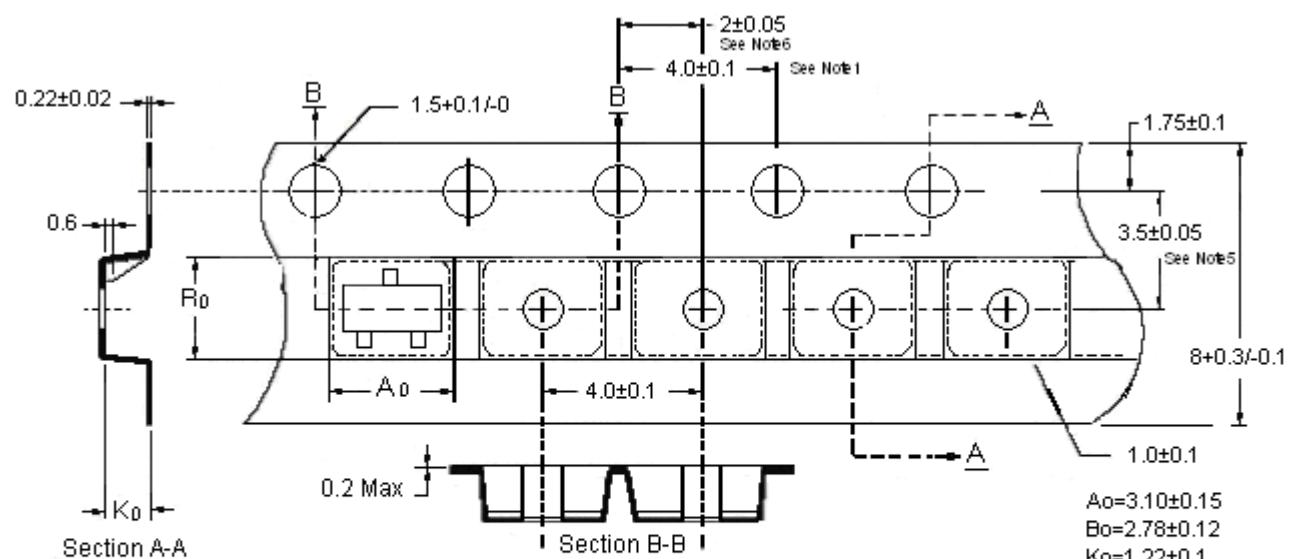


Reel Dimension



Unit: millimeter

Carrier Tape Dimension

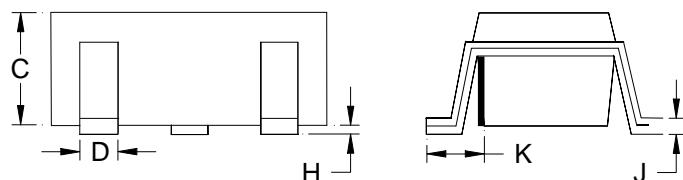
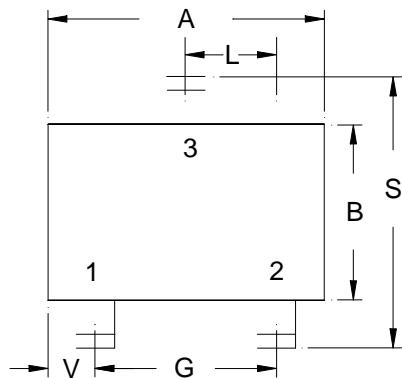


Notes:

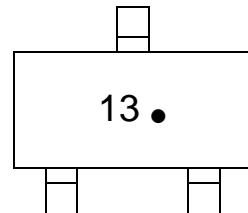
1. 10 sprocket hole pitch cumulative tolerance ± 0.2 .
2. Camber not to exceed 1mm in 100mm.
3. Material: conductive Black Polystyrene.
4. A_0 & B_0 measured on a plane 0.3mm above the bottom of the pocket.
5. K_0 measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

SOT-23 Dimension



Marking:



3-Lead SOT-23 Plastic
Surface Mounted Package
Package Code: N3

Style: Pin 1.Gate 2.Source 3.Drain

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0032	0.0079	0.08	0.20
B	0.0472	0.0669	1.20	1.70	K	0.0118	0.0266	0.30	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1161	2.10	2.95
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0000	0.0040	0.00	0.10					